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PTO/SB/21 (08-03)

Approved for use through 08/30/2003. OMB 0651-0031

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TRANSMITTAL FORM (to be used for all correspondence after initial filing)	Application Number	10/735,355
	Filing Date	December 12, 2003
	First Named Inventor	Zhongze Wang
	Art Unit	2811
	Examiner Name	Unknown
	Attorney Docket Number	MI22-2457
Total Number of Pages in This Submission		

ENCLOSURES (Check all that apply)		
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Signature	
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EV 372457972



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No. 10/735,355
Filing Date December 12, 2003
Inventorship Zhongze Wang
Assignee Micron Technology, Inc.
Group Art Unit 2811
Examiner Unknown
Attorney's Docket No. MI22-2457
Title: Wafer Bonding Method of Forming Silicon-on-Insulator Comprising
Integrated Circuitry

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT


References - See Attached Form PTO-1449


In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. Copies of the cited art are not included (1276 Off. Gaz. Pat. Off 55, 05 August 2003). No admission is made regarding whether all the submitted references are prior art.

This Supplemental Information Disclosure Statement is being filed within three months of the filing date of the application or before the mailing of a first Office Action on the merits, whichever occurs last. Therefore, no fee is believed to be required. However, in the event that a fee is required for filing this Supplemental Information Disclosure Statement, please charge the fee specified under 37 C.F.R. § 1.17(p) to Deposit Account No. 23-0925.

Respectfully submitted,

Dated: 6/22/04

By: 
Mark S. Matkin
Reg. No. 32,268

		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2457		SERIAL NO. 10/735,355	
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					
		APPLICANT: Zhongze Wang				FILING DATE 12/12/2003	

U.S. PATENT DOCUMENTS							
*Examiner's Initials	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
AA	6,552,496 B2	04/2003	Yamazaki	315	169.3		
AB	5,882,532	03/1999	Field et al.	216	2		
AC	6,265,327	07/2001	Kobayashi et al.	438	776		
AD							
AE							
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FOREIGN PATENT DOCUMENTS								
Document Number	Date	Country	Class	Subclass	Translation			
					Yes	No		
AJ								
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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)			
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